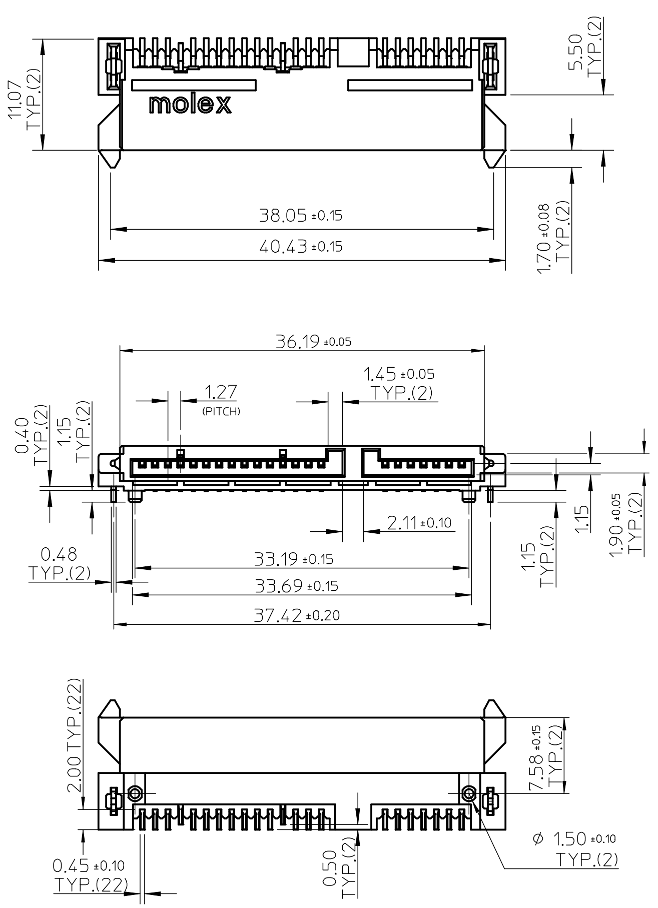
Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

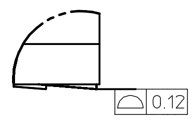
With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

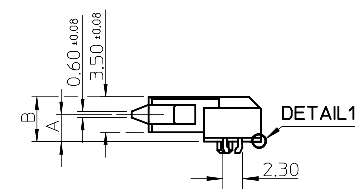
Contact us

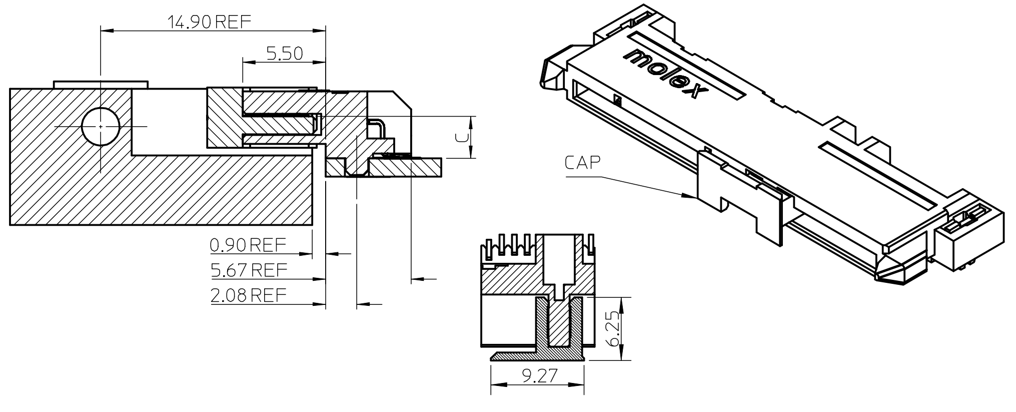
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



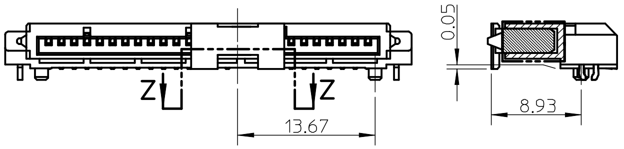


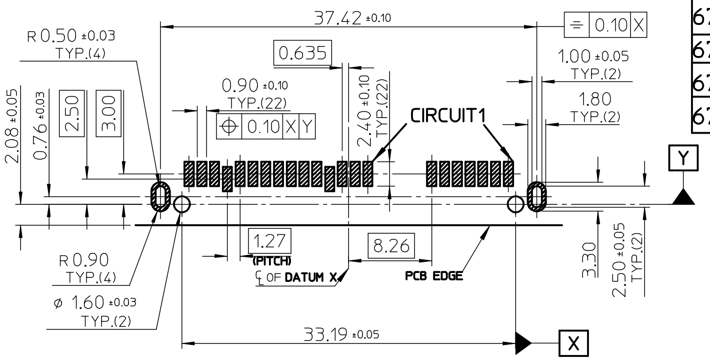
DETAIL1





SECTION Z-Z





RECOMMENDED P.C.B. LAYOUT (THICKNESS=1.2mm)

CONNECTOR SIDE

P/N	PLATING	DIM'A'	DIM'B'	DIM'C'	HUSING COLOR	REMARK
67492-1630	NOTES 2 (A)	2.70	4.45	2.80	BLACK	WITH CAP
67492-1631	NOTES 2 (B)					
67492-1632	NOTES 2 (C)					
67492-1730	NOTES 2 (A)	1.95	3.70	2.05	WHITE	
67492-1731	NOTES 2 (B)					
67492-1732	NOTES 2 (C)					
67492-1620	NOTES 2 (A)	2.70	4.45	2.80	BLACK	WITHOUT CAP
67492-1621	NOTES 2 (B)					
67492-1622	NOTES 2 (C)					
67492-1720	NOTES 2 (A)	1.95	3.70	2.05	WHITE	
67492-1721	NOTES 2 (B)					
67492-1722	NOTES 2 (C)					

NOTES:

1.MATERIAL:
- HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0, COLOR: REFER TO TABLE IN SHEET 2.
- TERMINAL: COPPER ALLOY;
- FORKLOCK: COPPER ALLOY.

2.TERMINAL PLATING :
- CONTACT AREA:
  - (A) GOLD FLASH;
  - (B) GOLD, THICKNESS=0.76 MICRONS MINIMUM;
  - (C) GOLD, THICKNESS=0.38 MICRONS MINIMUM;
- SOLDER AREA: TIN, THICKNESS=1.27 MICRONS MINIMUM;
- UNDER PLATE: NICKEL, THICKNESS=1.27 MICRONS MINIMUM.

3.FORKLOCK PLATING:
- SOLDER AREA: TIN, THICKNESS=1.27 MICRONS MINIMUM;
- UNDER PLATE: NICKEL, THICKNESS=1.27 MICRONS MINIMUM.

4.PRODUCT SPECIFICATION: REFER TO PS-67492-001.

5.PACKAGING METHOD: TAPE REEL, 67492-163* REFER TO PK-67492-005; 67492-173* REFER TO PK-67492-006.

6.MATING PARTS: 87703/87672.

EC NO:
DRWN:GLLI 2006/02/08
CH'KD: 2006/02/28
APPR:GRMA 2006/03/01
RTM
DESCRIPTION
B
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.15	± ---
1 PLACE	± 0.25	± ---

ANGULAR ± 3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	2:1	METRIC	THIRD ANGLE PROJECTION

		DATE
DRAWN BY	DIXON LI	2005/12/22
CHECKED BY	JANNY ZENG	2005/12/22
APPROVED BY	GRATE MA	2005/12/22

MATERIAL NO.
SEE TABLE

TITLE
SATA HOST RECEPTACLE R/A SMT TYPE -LEAD FREE-

molex MOLEX INCORPORATED

DOCUMENT NO.
SD-67492-008

SHEET NO.
1 OF 1

SIZE A3

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